

# Lonten N-channel 60V, 104A, 4.6mΩ Power MOSFET

### **Description**

These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

#### **Features**

- 60V,104A,  $R_{DS(on),max} = 4.6 \text{m}\Omega @V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- ♦ 100% EAS Guaranteed
- ◆ Green device available

### **Applications**

- Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

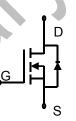
# **Product Summary**

 $\begin{array}{ll} V_{DSS} & 60V \\ R_{DS(on),max} \textcircled{0} \ V_{GS} \text{=} 10V & 4.6 \text{m} \Omega \\ I_D & 104A \end{array}$ 

## **Pin Configuration**



TO-263





N-Channel MOSFET

### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Continuous drain current ( Tc = 25°C )	1	104	А
( T <sub>C</sub> = 100°C )	I <sub>D</sub>	65	Α
Pulsed drain current <sup>1)</sup>	I <sub>DM</sub>	312	А
Gate-Source voltage	V <sub>GSS</sub>	±20	V
Avalanche energy <sup>2)</sup>	E <sub>AS</sub>	28	mJ
Power Dissipation	P <sub>D</sub>	89	W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R <sub>θ</sub> JC	1.4	°C/W
Thermal Resistance Junction-to-Ambient	R <sub>θJA</sub>	55	°C/W

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**Package Marking and Ordering Information** 

Device	Device Package	Marking	Units/Reel	
LSGE06R046HWB	TO-263	E06R046HWB	800	

### Electrical Characteristics T. = 25°C unless otherwise noted

Electrical Characteristics	T <sub>J</sub> = 25°C unle	ess otherwise noted				
Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	60			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2.0	3.0	4.0	V
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =60 V, V <sub>GS</sub> =0V			1	μA
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =20 V, V <sub>DS</sub> =0 V			100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-20 V, V <sub>DS</sub> =0 V			-100	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =20 A		3.6	4.6	mΩ
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		66		S
Dynamic characteristics						
Input capacitance	C <sub>iss</sub>	V 00 V V 0 V		3511		
Output capacitance	Coss	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$	2	1176		pF
Reverse transfer capacitance	C <sub>rss</sub>	F = 1MHz		67		
Turn-on delay time	t <sub>d(on)</sub>			20.3		
Rise time	tr	$V_{DD} = 30V, V_{GS} = 10V, I_D = 20A$		9.6		ns
Turn-off delay time	t <sub>d(off)</sub>	R <sub>G</sub> =3Ω		61		
Fall time	t <sub>f</sub>			15.2		
Gate resistance	Rg	V <sub>GS</sub> =0 V,V <sub>DS</sub> =0 V, F=1MHz		1.1		Ω
Gate charge characteristics						
Gate to source charge	Q <sub>gs</sub>	V -20V I -20A		15.5		
Gate to drain charge	Q <sub>gd</sub>	V <sub>DS</sub> =30V, I <sub>D</sub> =20A, V <sub>GS</sub> = 10 V		9.5		nC
Gate charge total	Qg	VGS- 10 V		48		
Drain-Source diode characterist	ics and Maxi	mum Ratings				
Continuous Source Current	ls				74	Α
Pulsed Source Current <sup>3)</sup>	Ism				222	Α
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A, T <sub>J</sub> =25℃			1.2	V
Reverse recovery time	trr	I <sub>F</sub> =20A,dI <sub>F</sub> /dt=100 A/µs		24		ns
Reverse recovery charge	Qrr	1;-20A,u1;/u1-100 A/μ5		85		nC

#### Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2:  $V_{DD}$ =50V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =24A, Starting  $T_J$ =25  $^{\circ}$ C.
- 3: Pulse Test: Pulse Width  $\leq 300 \, \mu \, \text{s}$ , Duty Cycle  $\leq 2\%$ .

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# **Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

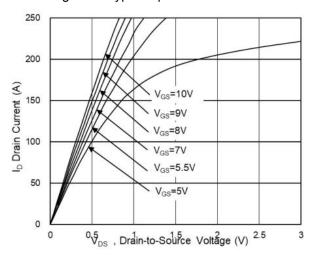


Figure 3. Capacitance Characteristics

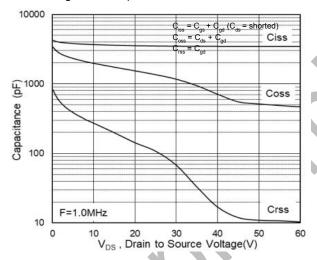


Figure 5. Body-Diode Characteristics

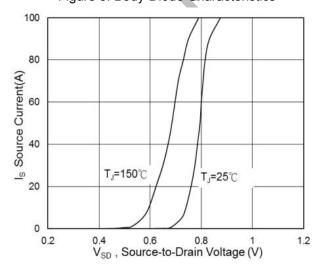


Figure 2. Transfer Characteristics

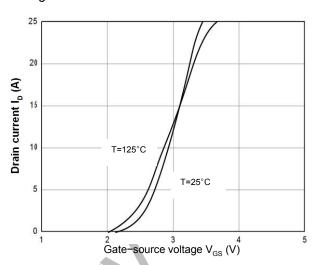


Figure 4. Gate Charge Waveform

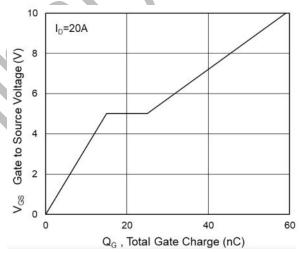


Figure 6. Rdson-Drain Current

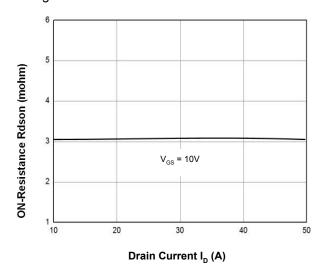




Figure 7. Rdson-Junction Temperature

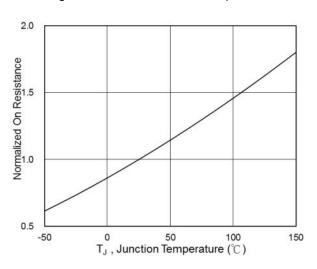


Figure 8. V<sub>GS(th)</sub>-Junction Temperature

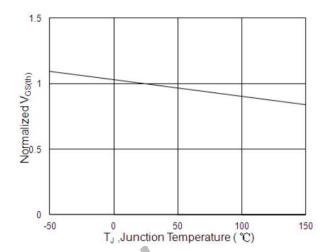


Figure 9. On-Resistance vs. Gate-to-Source voltage

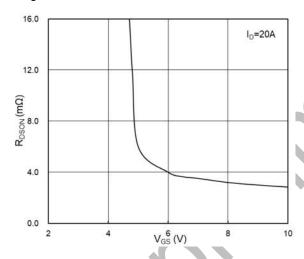


Figure 10: Safe Operating Area

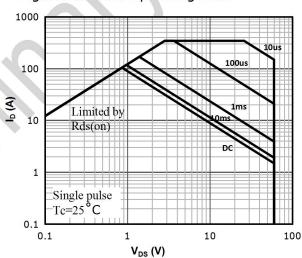
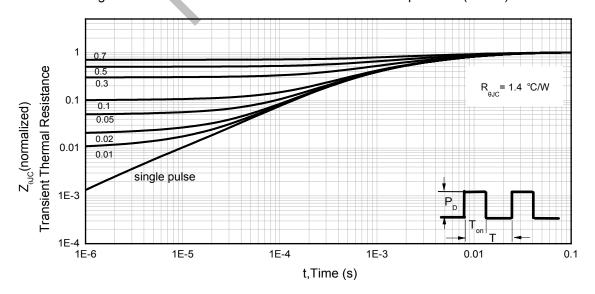


Figure 11. Normalized Maximum Transient Thermal Impedance (RthJC)

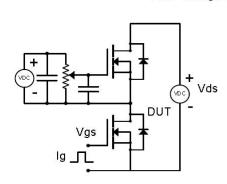


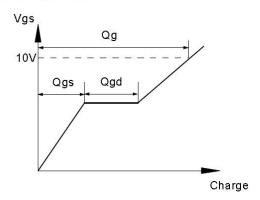
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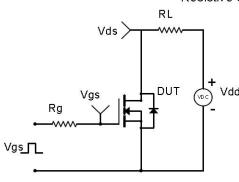
# **Test Circuit & Waveform**

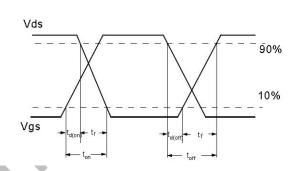
# Gate Charge Test Circuit & Waveform



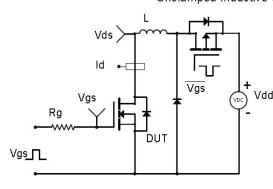


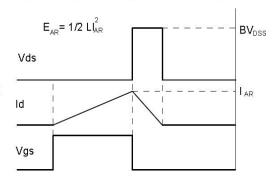
Resistive Switching Test Circuit & Waveforms



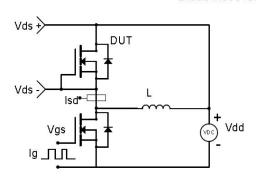


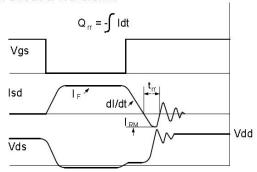
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





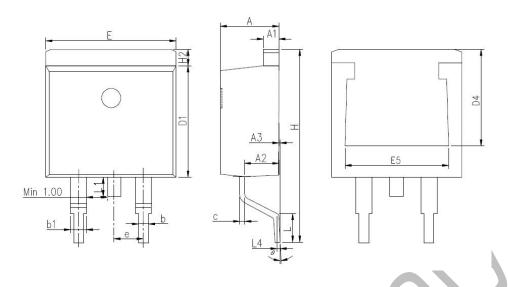
### Diode Recovery Test Circuit & Waveforms







# **Mechanical Dimensions for TO-263**



DIMENSION	IS IN MILL	ITMETERS	DIMENSIONS IN INCHES		
SYMBOL	MIN	MAX	MIN	MAX	
A	4. 36	4.8	0. 172	0. 189	
A1	1. 19	1. 42	0.047	0.056	
A2	2. 2	2. 96	0.087	0. 117	
А3	0	0. 25	0	0.010	
b	0.7	0.96	0. 028	0. 038	
b1	1. 17	1.47	0.046	0.058	
С	0.3	0. 69	0.012	0. 027	
D1	8. 5	9. 5	0. 335	0. 374	
D4	6.6	-	0. 260	_	
Е	9.8	10. 55	0. 386	0. 415	
E5	7. 06	8. 7	0. 278	0. 343	
е	2. 5	2. 54BSC		0. 1BSC	
Н	14. 7	15. 7	0. 579	0.618	
Н2	0. 95	1.65	0. 037	0.065	
L	1. 9	2.8	0.075	0. 110	
L1	-	1. 78	-	0.070	
L4	0. 2	25BSC	0. 01BSC		
θ	0°	9°	0°	9°	



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
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BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
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